

LINEAR TECHNOLOGY MATERIALS DECLARATION

1tc3624hmse-2#pbf

(Engineering Calculation)

MSOP-Exposed

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TOTAL MASS (g) : 0.03669

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.001892 | 1000000 | 51567.1523438 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.013845 | 975000 | 377350.53125 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000341 | 24000 | 9294.08007812 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000004 | 300 | 109.021461487 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000010 | 700 | 272.553649902 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.014200 | 1000000 | 387026.1875 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000710 | 1000000 | 19351.9902344 | | |
| | | External Plating Total: | | | | 0.000710 | 1000000 | 19351.9902344 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000086 | 1000000 | 2343.96142578 | | |
| Internal Plating Total: | | | | 0.000086 | 1000000 | 2343.96142578 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000680 | 750000 | 18533.6484375 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000227 | 250000 | 6186.96826172 | | |
| Die Attach Total: | | | | 0.000907 | 1000000 | 24720.6171875 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.002439 | 130000 | 66475.8359375 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.015571 | 830000 | 424393.28125 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000657 | 35000 | 17906.7753906 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000094 | 5000 | 2562.00439453 | | |
| | | Encapsulation Total: | | | | 0.018761 | 1000000 | 511337.9375 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000134 | 1000000 | 3652.21923828 | | |
| | | | | | TOTAL MASS (g) : | 0.03669 | | |